

SMD Auto COG HV Flex, Ceramic, 1000 pF, 5%, 630 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, Automotive Grade, 1206



Dimensions

| Dimensions | |
|------------|-----------------|
| Chip Size | 1206 |
| L | 3.3mm +/-0.4mm |
| W | 1.6mm +/-0.35mm |
| T | 1.2mm +/-0.15mm |
| B | 0.6mm +/-0.25mm |

Packaging Specifications

| | |
|---------------------|--------------------------|
| Packaging: | T&R, 180mm, Plastic Tape |
| Packaging Quantity: | 2500 |

General Information

| | |
|-------------------|---|
| Series: | SMD Auto COG HV Flex |
| Style: | SMD Chip |
| Description: | SMD, MLCC, FT-CAP, Ultra-Stable, Automotive Grade |
| Features: | FT-CAP, Ultra-Stable, Automotive Grade |
| RoHS: | Yes |
| Termination: | Flexible Termination |
| Marking: | No |
| Qualifications: | AEC-Q200 |
| AEC-Q200: | Yes |
| Component Weight: | 30 mg |
| Shelf Life: | 78 Weeks |
| MSL: | 1 |

Specifications

| | |
|---|---------------------------|
| Capacitance: | 1000 pF |
| Measurement Condition: | 1 MHz 1.0Vrms |
| Capacitance Tolerance: | 5% |
| Voltage DC: | 630 VDC |
| Dielectric Withstanding Voltage: | 945 VDC |
| Temperature Range: | -55/+125°C |
| Temperature Coefficient: | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC): | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor: | 0.1% 1 MHz 1.0Vrms |
| Aging Rate: | 0% Loss/Decade Hour |
| Insulation Resistance: | 100 GOhms |